

REMARKS

Applicant would like to thank the Examiner for the thorough consideration given to the present application. Claims 1-5 and 29 remain pending in the present application. Claim 29 has been added to the present application. The basis for the above amendments may be found throughout the specification, drawings and claims as originally filed. The Examiner is respectfully requested to reconsider and withdraw his rejections in view of the above amendments and remarks as set forth below.

REJECTIONS UNDER 35 USC §102

Claims 1-5 stand rejected under 35 USC §102(e) as being unpatentable over U.S. Patent No. 6,255,741 (Yoshihara). Applicant respectfully traverses this rejection.

Yoshihara is directed generally to a semiconductor chip having a protective cap. Of particular interest, Yoshihara discloses an adhesive sheet 20 having a resin sheet 2 and an adhesive portion 3. As shown in Figure 2B, the adhesive portion 3 is not disposed substantially on an entire surface of the sheet member. On the contrary, recesses 20a are formed on the heat resisting adhesive sheet 20 so that beam structures 1a can be prevented from contacting the heat resisting adhesive sheet 20 (see col. 4, lines 34-38). Moreover, Yoshihara does not teach or suggest a specific region of the adhesive portion having a less adhesive characteristic.

Applicant's claimed invention is similarly directed to a semiconductor device having an adhesive sheet detachably attached thereto. However, Claim 1 recites that the "adhesive portion provided substantially on an entire surface of the sheet member". Claim 1 further recites "the adhesive portion having a specific region having an adhesion smaller than that of a vicinal region of the adhesive portion surrounding the specific region". Unlike Yoshihara, the specific regions(s) are arranged to oppose the sensing portions 3 of the semiconductor device, thereby providing a more effective protective cap. Therefore, it is respectfully submitted that Claim 1, along with the claims depending therefrom, are patentability distinct over Yoshihara.

Applicant also notes that Yoshihara does not teach or suggest that the adhesive portion is made of a UV setting adhesive, such that a specific region of the adhesive portion can be easily reduced by UV radiation. Examiner's attention is drawn to additional claims depending from Claim 1 which are directed to this aspect of applicant's invention. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this rejection.

CONCLUSION

All of the stated grounds for rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider all presently outstanding rejections and further requests that they be withdrawn. Accordingly, it is believed that a full and complete response has been made to the outstanding Office Action and, as such, the present application is in condition for allowance. If the Examiner believes that personal communication will expedite prosecution of this application, he is invited to telephone the undersigned at (248) 641-1230.

Prompt and favorable consideration of this response is respectfully requested.

Respectfully submitted,

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